Tin Whisker Mitigation strategies are necessary due to the well known phenomenon of whisker growth associated with use of a number of low melting point elements, including tin, in operations such as soldering. This phenomenon was recognized by the electronics industry several years ago, and the problem was minimized by the addition of lead to the soldering process. For environmental health concerns, lead has been identified as a hazardous substance, and soldering has migrated to lead-free. This has brought Tin Whisker Mitigation to the forefront, and Vicor has instituted a Tin Whisker Mitigation Program to maintain the high quality and reliability of its products. This program is described in the following documents.

CST-0012 – Vicor Tin Whisker Mitigation Program
CST-0013 – First Generation Product Family Component Lead Finish
CST-0014 – FasTrak Product Family Component Lead Finish
CST-0015 – VIChip Product Family Component Lead Finish